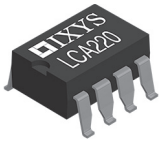
IXYS
INTEGRATED CIRCUITS DIVISION



LCA220
Normally Open, Double-Pole, Single-Throw OptoMOS® Relay

Parameter	Ratings	Units
Blocking Voltage	250	V_P
Load Current	120	mA_{rms} / mA_{DC}
On-Resistance (max)	20	Ω

Features

- 3750V_{rms} Input/Output Isolation
- Low Drive Power Requirements
- High Reliability
- Arc-Free With No Snubbing Circuits
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- Small 8-Pin Package
- Surface Mount Tape & Reel Version Available
- Flammability Rating UL 94 V-0

Applications

- Telecommunications
  - Telecom Switching
  - Tip/Ring Circuits
  - Modem Switching (Laptop, Notebook, Pocket Size)
  - Hook Switch
  - Dial Pulsing
  - Ground Start
  - Ringing Injection
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

LCA220 is a normally open, double-pole, single-throw (2-Form-A) solid state relay that has two optically coupled MOSFET switches controlled by a common input signal. It is provided in an 8-pin package, and employs optically coupled MOSFET technology to provide 3750V_{rms} of input to output isolation.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

Common-input OptoMOS relays can replace standard dual, single-throw relays in a variety of applications. The common-input relay eliminates the need to make a second circuit connection when both poles are controlled by the same signal.

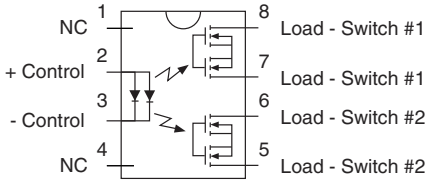
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN/IEC 60950-1 Certified Component: Certificate available on our website

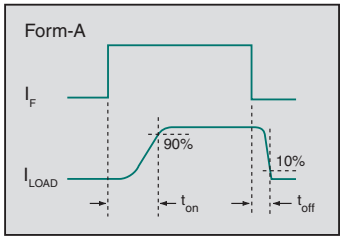
Ordering Information

Part #	Description
LCA220	8-Pin DIP (50/Tube)
LCA220S	8-Pin Surface Mount (50/Tube)
LCA220STR	8-Pin Surface Mount (1,000/Reel)

Pin Configuration



Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings T_A=25ºC

Parameter	Symbol	Ratings	Units
Blocking Voltage	V_B	250	V_P
Reverse Input Voltage	V_R	5	V
Input Control Current Peak (10ms)	I_F	100	mA
		1	A
Input Power Dissipation [1]	P_I	150	mW
Total Power Dissipation [2]	P_D	800	mW
Isolation Voltage, Input to Output	V_{ISO}	3750	V_{rms}
Operational Temperature	T_A	-40 to +85	°C
Storage Temperature	T_{STG}	-40 to +125	°C

[1] Derate linearly 1.33 mW / ºC

[2] Derate linearly 6.67 mW / ºC

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

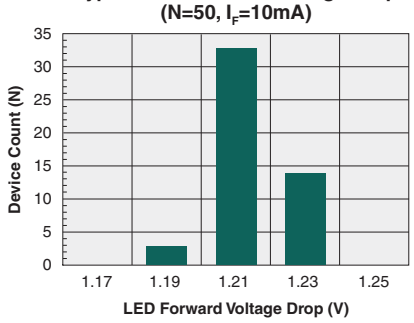
Electrical Characteristics T_A=25ºC

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current						
Continuous	-	I_L	-	-	120	mA_{rms} / mA_{DC}
Peak	t=10ms	I_{LPK}	-	-	±340	mA_P
On-Resistance [1]	I_L=120mA	R_{ON}	-	-	20	Ω
Off-State Leakage Current	V_L=250V_P	I_{LEAK}	-	-	1	µA
Switching Speeds						
Turn-On	I_F = 10mA, V_L = 10V	t_{on}	-	-	5	ms
Turn-Off		t_{off}	-	-	5	ms
Output Capacitance	I_F=0mA, V_L=50V, f=1MHz	C_{OUT}	-	50	-	pF
Input Characteristics [2]						
Input Control Current to Activate	I_L = 120mA	I_F	-	-	10	mA
Input Control Current to Deactivate	-	I_F	0.8	1.4	-	mA
Input Voltage Drop	I_F = 10mA	V_F	0.9	1.2	1.5	V
Reverse Input Current	V_R = 5V	I_R	-	-	20	µA
Common Characteristics						
Capacitance, Input to Output	V_{IO}=0V, f=1MHz	C_{IO}	-	3	-	pF

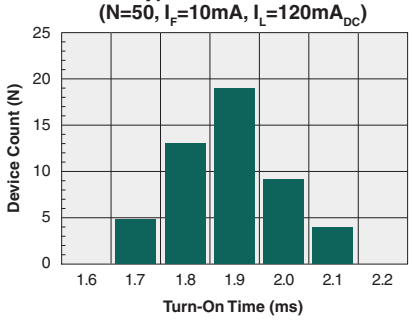
[1] Measurement taken within 1 second of on-time.
[2] Input characteristics represent requirements of two parallel-connected LEDs.

PERFORMANCE DATA*

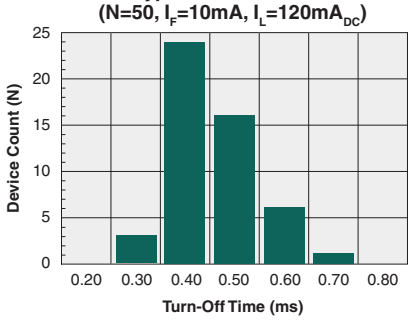
Typical LED Forward Voltage Drop
(N=50, I_F=10mA)



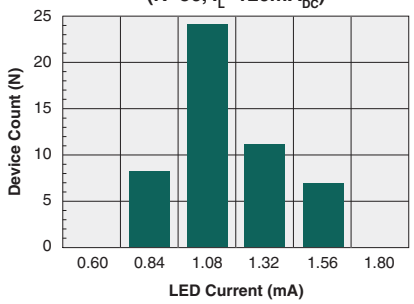
Typical Turn-On Time
(N=50, I_F=10mA, I_L=120mA$_{DC}$)



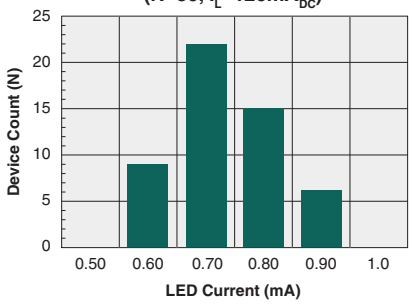
Typical Turn-Off Time
(N=50, I_F=10mA, I_L=120mA$_{DC}$)



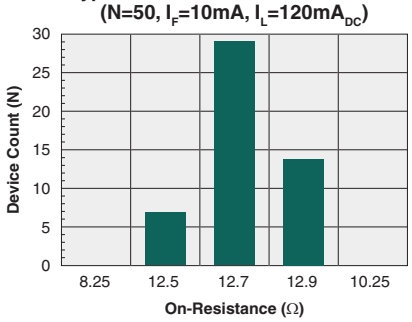
Typical I_F for Switch Operation
(N=50, I_L=120mA$_{DC}$)



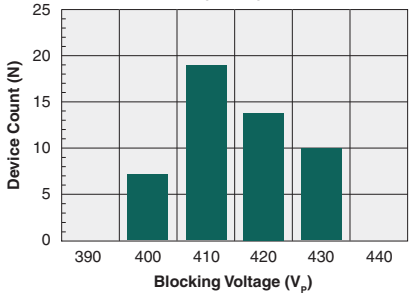
Typical I_F for Switch Dropout
(N=50, I_L=120mA$_{DC}$)



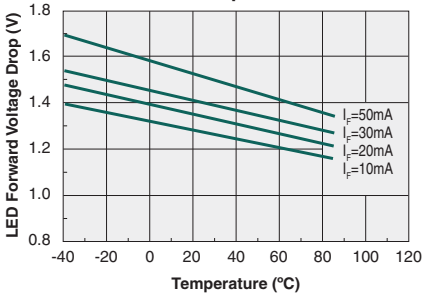
Typical On-Resistance Distribution
(N=50, I_F=10mA, I_L=120mA$_{DC}$)



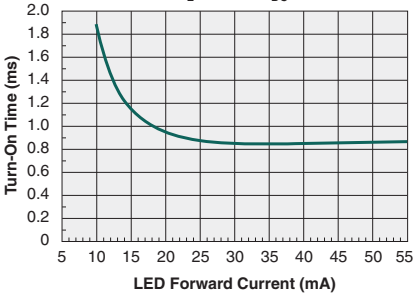
Typical Blocking Voltage Distribution
(N=50)



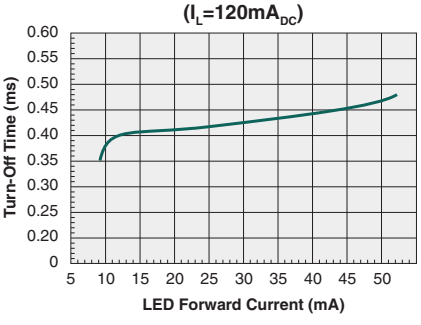
Typical LED Forward Voltage Drop
vs. Temperature



Typical Turn-On Time
vs. LED Forward Current
(I_L=120mA$_{DC}$)



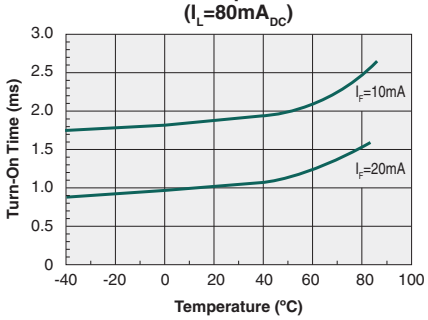
Typical Turn-Off Time
vs. LED Forward Current
(I_L=120mA$_{DC}$)



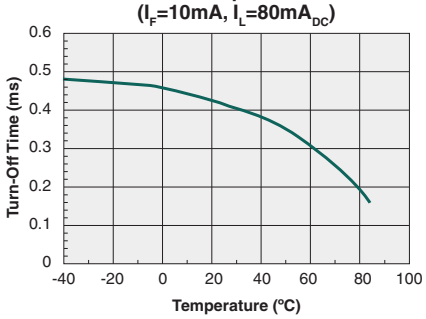
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA*

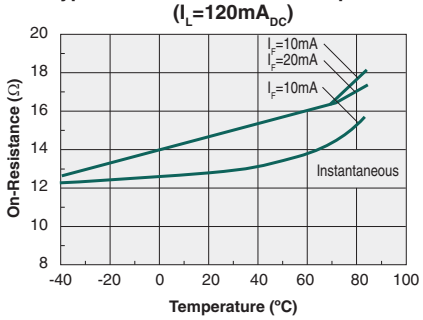
Typical Turn-On Time vs. Temperature (I_L=80mA$_{DC}$)



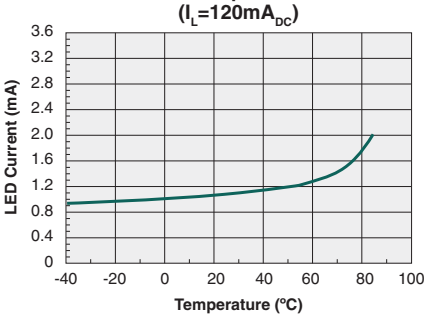
Typical Turn-Off Time vs. Temperature (I_F=10mA, I_L=80mA$_{DC}$)



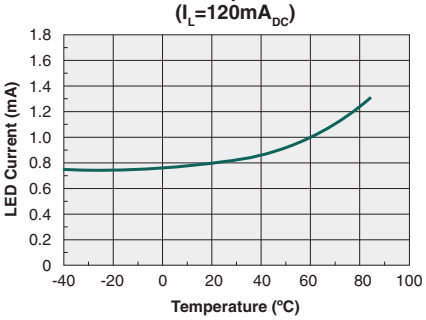
Typical On-Resistance vs. Temperature (I_L=120mA$_{DC}$)



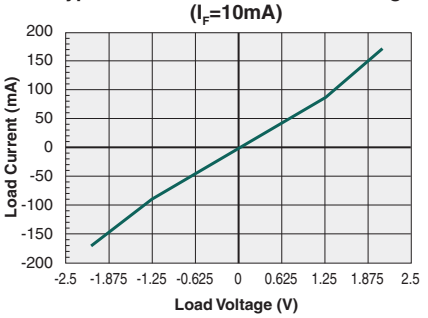
Typical I_F for Switch Operation vs. Temperature (I_L=120mA$_{DC}$)



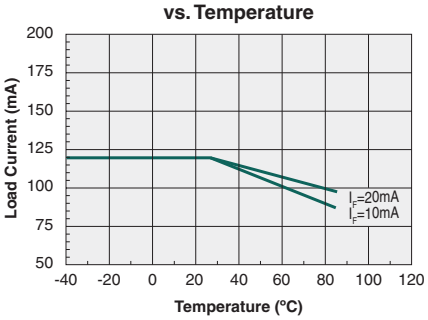
Typical I_F for Switch Dropout vs. Temperature (I_L=120mA$_{DC}$)



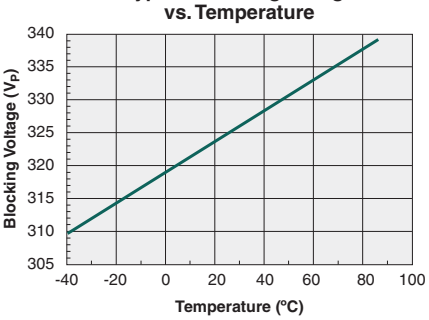
Typical Load Current vs. Load Voltage (I_F=10mA)



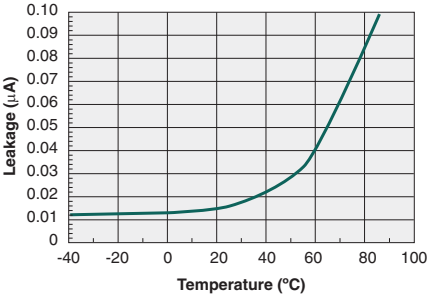
Maximum Load Current vs. Temperature



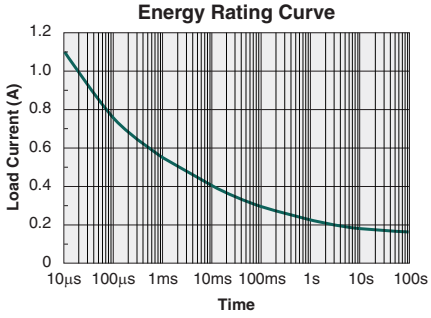
Typical Blocking Voltage vs. Temperature



Typical Leakage vs. Temperature Measured across Pins 5&6 or 7&8



Energy Rating Curve



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
LCA220 / LCA220S	MSL 1

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)ºC or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

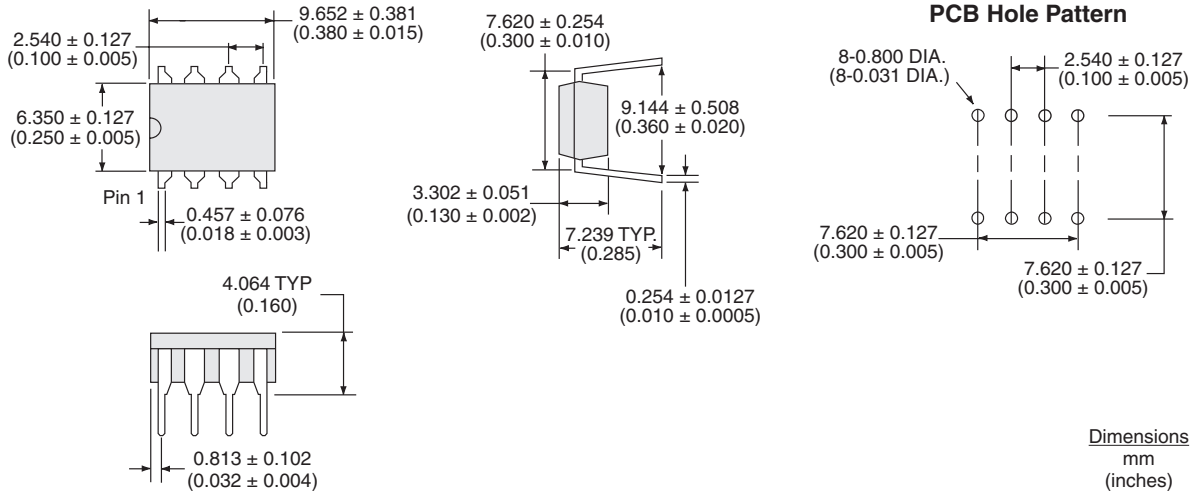
Device	Classification Temperature (T_c)	Dwell Time (t_p)	Max Reflow Cycles
LCA220S	250ºC	30 seconds	3
LCA220	250ºC	30 seconds	1

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

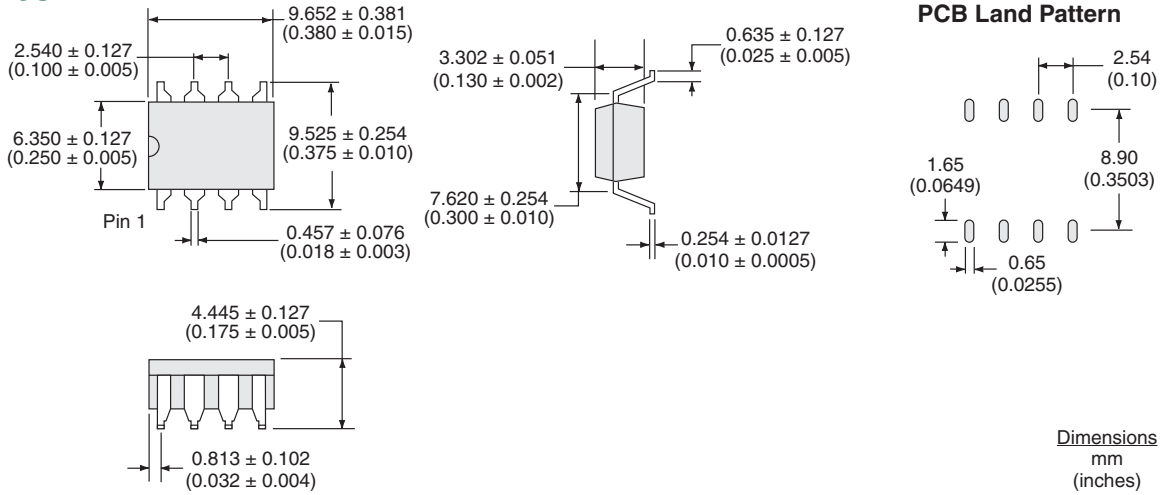
MECHANICAL DIMENSIONS

LCA220



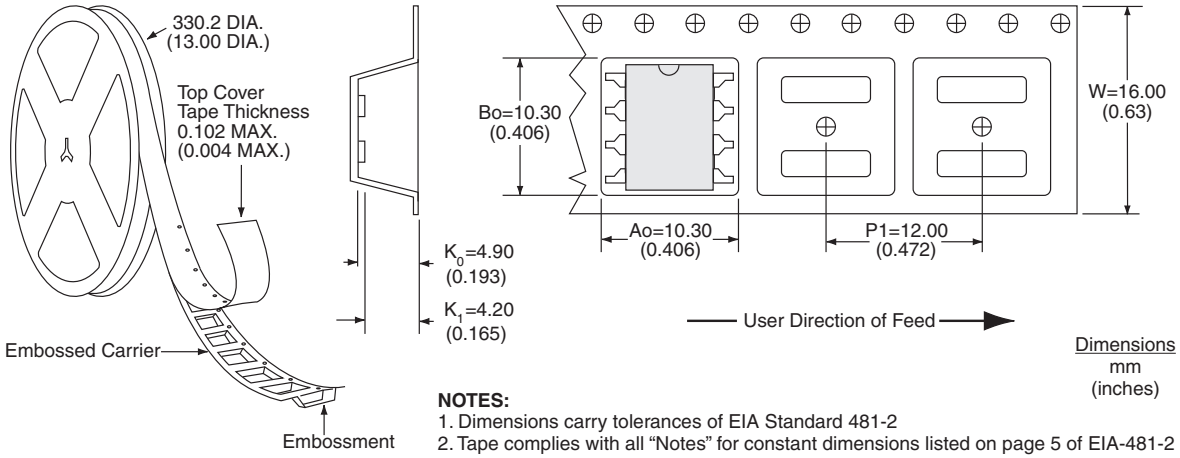
Dimensions
mm
(inches)

LCA220S



Dimensions
mm
(inches)

LCA220STR Tape & Reel



NOTES:
1. Dimensions carry tolerances of EIA Standard 481-2
2. Tape complies with all "Notes" for constant dimensions listed on page 5 of EIA-481-2

For additional information please visit our website at: www.ixysic.com

Specification: DS-LCA220-R08

9/21/2018